

ABSTRACT

SYSTEM FOR DIFFERENT BOND PADS IN AN INTEGRATED CIRCUIT PACKAGE

An integrated circuit package and method for manufacturing is provided with a substrate having first and second contact pads exposed through a passivation layer on the substrate. A first metallurgy layer is formed over the substrate. A second metallurgy layer is formed over the first metallurgy layer. The first metallurgy layer is removed while leaving a portion thereof over the second contact pad. The second metallurgy layer is removed while leaving a portion thereof over the second contact pad. A protective layer is formed over the first contact pad while removing the second metallurgy layer. (Fig. 2)